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HIGH-DENSITY MOUNTING METHOD

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[There are no amendments to this patent.]

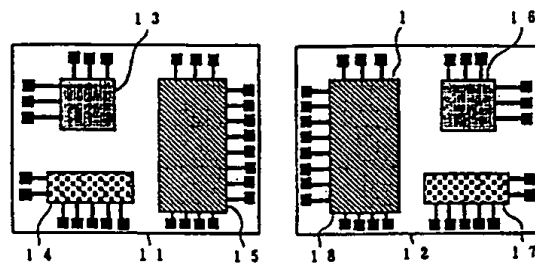
Abstract

Purpose

To mount semiconductor elements with high mounting density.

Constitution

The pin arrangements of semiconductor elements 11 and 12 are such that, when said semiconductor elements are stacked [facing each other], of these semiconductor elements occupy the same position.



Claims

1. A high-density mounting method in which multiple semiconductor elements are mounted, characterized in that the wiring of each of the aforementioned multiple semiconductor elements is formed such that, when stacked [facing each other], the pins of the aforementioned multiple semiconductor elements will occupy the same positions.

2. The high-density mounting method of Claim 1, wherein the
aformentioned multiple semiconductor elements are on a substrate.

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